

<b>Notice of References Cited</b>	Application/Control No. 10/604,572	Applicant(s)/Patent Under Reexamination DAUBENSPECK ET AL.	
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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	J. Lumsden et al., "An AC Impedance In Situ Methodology for Assessing High Reliability Performance of Plastic Encapsulated Microelectronics in Harsh Environments," May 2002, Electronic Components and Technology Conference, pages 219-224.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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